

WAFER CONVEYING DEVICE

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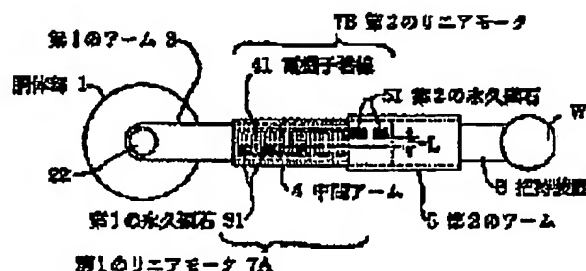
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Abstract of JP11138471

PROBLEM TO BE SOLVED: To provide a compact wafer conveying device. **SOLUTION:** A wafer conveying device is provided with a driving motor housed in a hollow body part 1, an output shaft 22 to be driven by the driving motor, a first arm 3 having one end fixed to the output shaft 22 and extending in the horizontal direction, and a second arm 5 to be straight moved along the first arm 3 and provided with a gripping device 6 on its tip. An intermediate arm 4 extending in the longitudinal direction of the first arm 3 is provided between the first arm 3 and the second arm 5, a first linear motor 7A for driving the intermediate arm 4 is formed of first permanent magnets 31 provided on the first arm 3 and a sheet-like armature winding 41 provided on the intermediate arm 4, and a second linear motor 7B for driving the second arm 5 is formed of the armature winding 41 and second permanent magnets 51 provided on the second arm 5. Accordingly, the longitudinal lengths of the first and second arms can be shortened to approximately 2/3 of the conventional structure.



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